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SEMI-THERM 29

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EXECUTIVE BRIEFING: THERMAL MANAGEMENT MARKET VISIONS & STRATEGIES

CONTENTS

AGENDA

TABLE TOP EXHIBITOR DIRECTORY

PARTICIPANT BIOGRAPHIES

PRESENTATIONS

- **TRENDS AND COMPETITIVE ACTIVITY IN THERMAL MANAGEMENT R&D**
  Kevin M. Closson, Senior Analyst, Nerac, Inc.

- **ARE YOU LEVERAGING DOD FUNDING?**
  Kenneth E. Goodson, Ph.D., Professor and Vice Chair of Mechanical Engineering, Stanford University

- **EMERGING TRENDS FOR THERMALLY CONDUCTIVE MATERIALS IN ELECTRONICS PACKAGING**
  Radesh Jewram, Sr. R&D Engineer, The Berquist Company

- **THERMAL MANAGEMENT IN THE "3D-SIP" WORLD OF THE FUTURE**
  Wilmer (Bill) R. Bottoms, Ph.D., President, 3MTS

- **LED LIGHTING - A HOT TOPIC WITH A BRIGHT FUTURE**
  Pat Bournes, Senior Development Engineer for Packaging, Philips Lumileds

- **DATACENTER AND SERVER THERMAL TRENDS AND CHALLENGES**
  David Copeland, DrEng, Thermal Engineering, Packaging Technology, Oracle Corporation

- ***KEYNOTE ADDRESS:* WHAT BURNS ME UP?**
  Roger Stout, PE, Research Scientist, Packaging Technology, Corporate R&D, ON Semiconductor

- **INCREASED PERFORMANCE FROM A LEGACY SYSTEM**
  Patrick Loney, Fellow Mechanical Engineer, Northrop Grumman Electronics Systems

- **THERMAL CHALLENGES OF COMPLEX FPGA/3D ICS FOR SPACE APPLICATIONS**
  Reza Ghaffarian, Ph.D., Principal Engineer, Jet Propulsion Laboratory, California Institute of Technology

- **COMMUNICATIONS: EVOLUTION OR REVOLUTION?**
  Dave Redford, Principal Network Design Engineer, Thermal Management SME, Global Engineering Support, AT&T NPE

- **MOBILE PHONE THERMAL DESIGN ANALYSIS**
  Sam Z. Zhao, Associate Technical Director, Broadcom Corporation

- **THERMAL MANAGEMENT CHALLENGES IN MOBILE INTEGRATED SYSTEMS**
  Ilyas Mohammed, Sr. Director and Principal Technologist, Invensas

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